



**YUYUE**

# HBS808 THRU HBS810

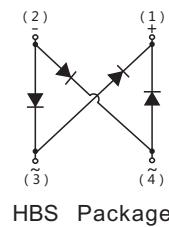
## 8A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

### FEATURES:

Surface mount bridge, small package;  
Ideal for printed circuit boards;  
Glass passivated chip junction;  
High forward current capability up to 8.0A;  
High surge current capability;  
High heat dissipation capability;  
Low profile package;  
Low forward voltage drop;  
Plastic package has Underwriters Laboratory  
Flammability Classification 94V-0;

### MECHANICAL DATA

Case: HBS;  
Epoxy meets UL-94V-0 Flammability rating;  
Terminals: Matte tin plated leads, solderable per  
J-STD-002 and JESD22-B102;  
High temperature soldering guaranteed:  
Solder Reflow 260 °C, 10seconds;  
Polarity: As marked on body;  
Marking: Type number;



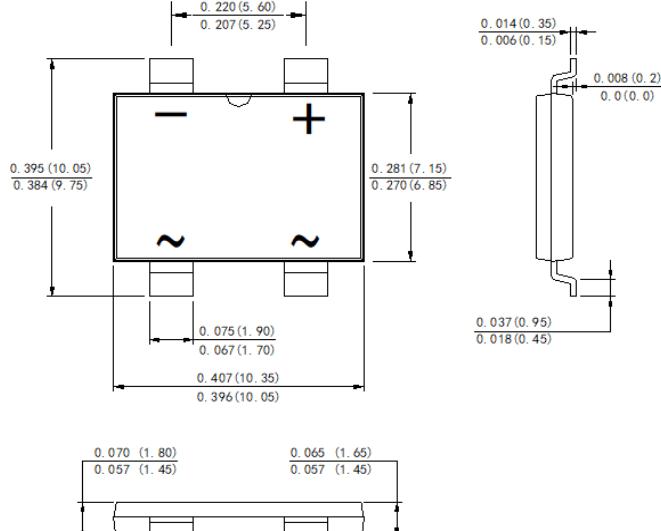
### VOLTAGE RANGE

800 to 1000 Volts

### CURRENT

8.0 Amperes

HBS



### Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

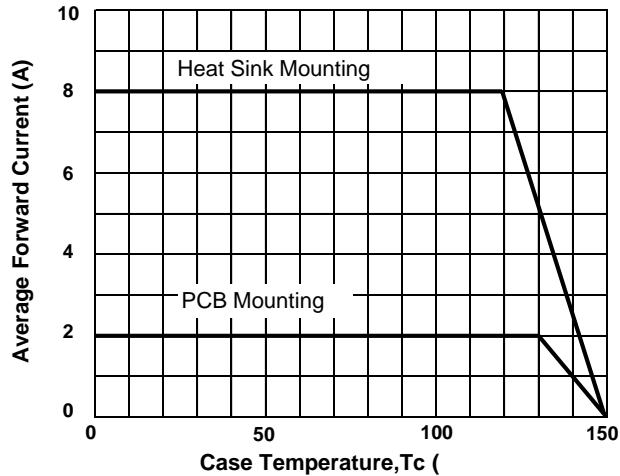
| Parameter   | Symbols                             | HBS808         | HBS810 | Units |
|---|-------------------------------------|----------------|--------|-------|
| Maximum Repetitive Peak Reverse Voltage   | $V_{RRM}$                           | 800            | 1000   | V     |
| Maximum RMS voltage   | $V_{RMS}$                           | 560            | 700    | V     |
| Maximum DC Blocking Voltage   | $V_{DC}$                            | 800            | 1000   | V     |
| Average Rectified Output Current  | $I_O$                               | 8.0            |        |       |
| Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method) | $I_{FSM}$                           | 220            |        |       |
| $I^2t$ Rating for Fusing  | $I^2t$                              | 170            |        |       |
| Maximum Forward Voltage at 1.0 A  | $V_F$                               | 0.81 (typ.)    |        |       |
| Maximum Forward Voltage at 8.0 A  | $V_F$                               | 1.0            |        |       |
| Maximum DC Reverse Current @ $T_A=25^\circ C$ @ $T_A=125^\circ C$                                 | $I_R$                               | 5<br>100       |        |       |
| Typical Junction Capacitance ( Note1 )  | $C_J$                               | 60             |        |       |
| Typical Thermal Resistance ( Note2 )  | $R_{BJA}$<br>$R_{BJC}$<br>$R_{BJL}$ | 60<br>10<br>12 |        |       |
| Operating and Storage Temperature Range   | $T_j, T_{stg}$                      | -55 ~ +150     |        |       |
|   |                                     |                |        |       |

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

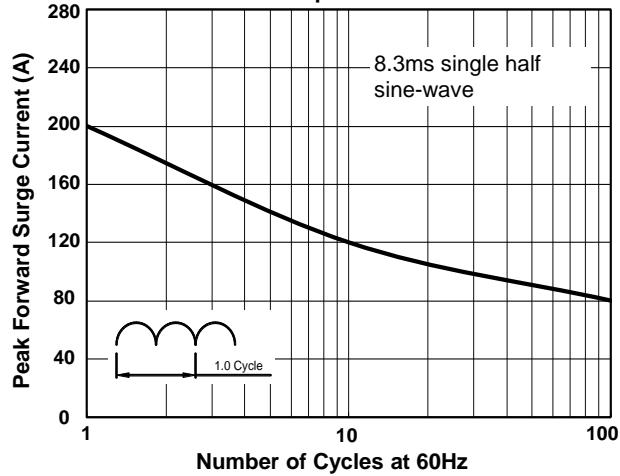
2. Mounted on glass epoxy PC board with 4×1.5"×1.5" ( 3.81×3.81 cm ) copper pad.

## RATING AND CHARACTERISTIC CURVES (HBS808 THRU HBS810)

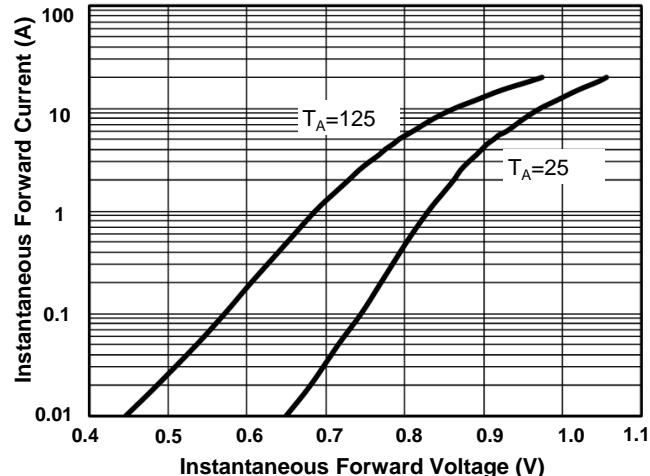
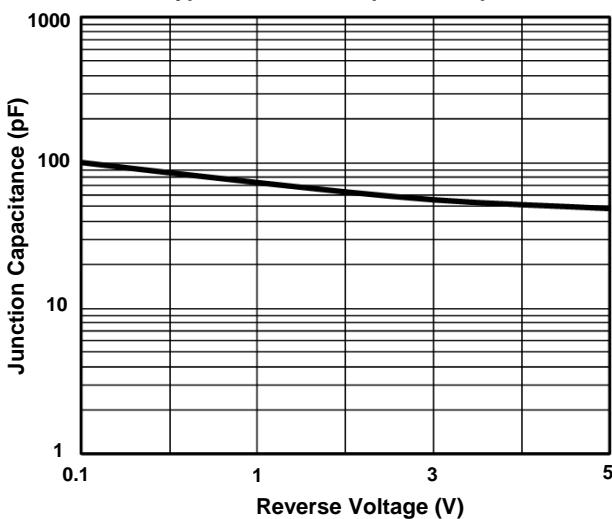
**FIG.1 Derating Curve Output Rectified Current**



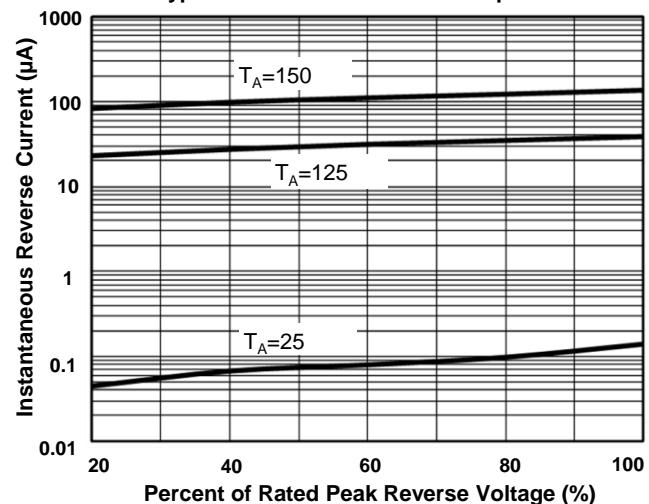
**FIG.3 Maximum Non-Repetitive Peak Forward Surge Current per Diode**



**FIG.5 Typical Junction Capacitance per Diode**



**FIG.4 Typical Reverse Characteristics per Diode**



**Suggested PCB printfoot layout**

Unit: inches (mm)

